Engineering/Process Change Notice

ECN/PCN No.: 4153

For Manufacturer			
Product Description: PLASTIC SMD MEMS OSCILLATOR	**Abracon Part Number / Part Series:** EMS12	☐ Documentation only ☐ ECN ☒ EOL	☒ Series ☐ Part Number
Affected Revision: E	**New Revision:** EOL	**Application:**	☐ Safety ☒ Non-Safety
Prior to Change: Active			
After Change: EOL			
Cause/Reason for Change: Discontinuation of manufacturing capability.			

Change Plan		
Effective Date: 2/7/2022	**Additional Remarks:** N/A	
Change Declaration: N/A		
Issued Date: 2/7/2022	**Issued By:** *Brooke Cushman* *Product Engineer*	**Issued Department:** Engineering
Approval: *Thomas Culhane* Engineering Director	**Approval:** *Reuben Quintanilla* Quality Director	**Approval:** *Ying Huang* Purchasing Director

For Abracon EOL only		
Last Time Buy (if applicable): 5/7/2022	**Alternate Part Number / Part Series:** ASSVP	
Additional Approval:	**Additional Approval:**	**Additional Approval:**

Customer Approval (If Applicable)		
Qualification Status: ☐ Approved ☐ Not accepted *Note: It is considered approved if there is no feedback from the customer 1 month after ECN/PCN is released.*		
Customer Part Number:	**Customer Project:**	
Company Name:	**Company Representative:**	**Representative Signature:**
Customer Remarks:		

REGULATORY COMPLIANCE

Lead Free COMPLIANT | EU RoHS 2011/65 + 2015/863 COMPLIANT | China RoHS COMPLIANT | REACH SVHC COMPLIANT | DRC CONFLICT FREE

ITEM DESCRIPTION

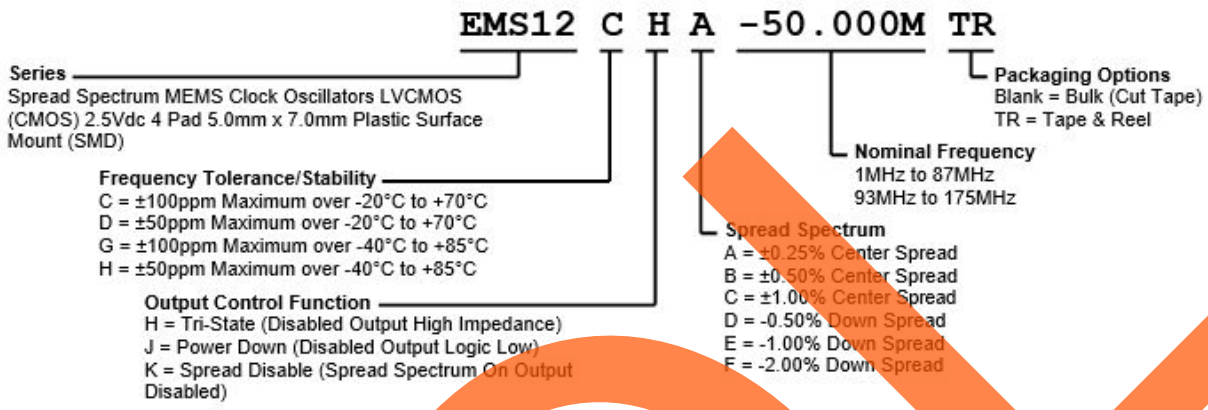
Spread Spectrum MEMS Clock Oscillators LVCMOS (CMOS) 2.5Vdc 4 Pad 5.0mm x 7.0mm Plastic Surface Mount (SMD)

ELECTRICAL SPECIFICATIONS

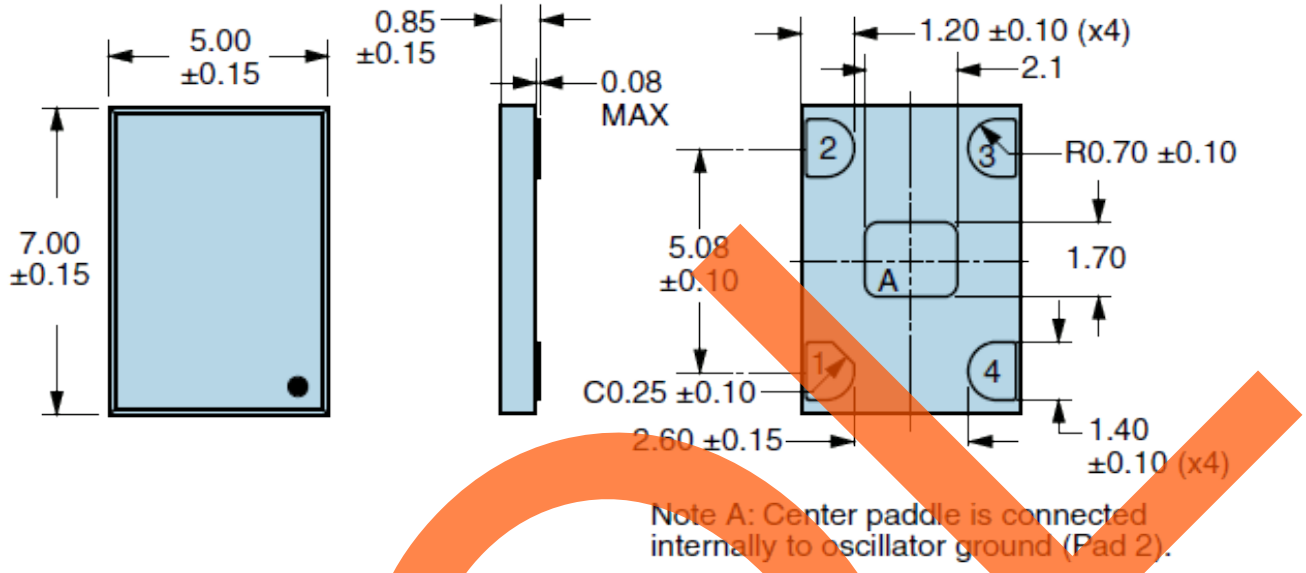
Nominal Frequency	1MHz to 175MHz
Frequency Tolerance/Stability	Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, 260°C Reflow, Shock, and Vibration ±100ppm Maximum over -20°C to +70°C ±50ppm Maximum over -20°C to +70°C ±100ppm Maximum over -40°C to +85°C ±50ppm Maximum over -40°C to +85°C
Aging at 25°C	±1ppm Maximum First Year
Supply Voltage	2.5Vdc ±10%
Maximum Supply Voltage	-0.5Vdc to +3.65Vdc
Input Current	Unloaded; Nominal Vdd 25mA Maximum over Nominal Frequency of 1MHz to 25MHz 35mA Maximum over Nominal Frequency of 25.000001MHz to 175MHz
Output Voltage Logic High (V_{Oh})	IOH=-8mA 90% of Vdd Minimum
Output Voltage Logic Low (V_{Ol})	IOL=+8mA 10% of Vdd Maximum
Rise/Fall Time	Measured from 20% to 80% of waveform 2nSec Maximum
Duty Cycle	Measured at 50% of waveform 50 ±5(%) over Nominal Frequency of 1MHz to 125MHz 50 ±10(%) over Nominal Frequency of 125.000001MHz to 175MHz
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Output Control Function	Tri-State (Disabled Output High Impedance) Power Down (Disabled Output Logic Low) Spread Disable (Spread Spectrum On Output Disabled)
Power Down Input Voltage (Vih and Vil)	70% of Vdd Minimum or No Connection to Enable Output, 30% of Vdd Maximum to Disable Output (Disabled Output Logic Low)
Tri-State Input Voltage (Vih and Vil)	70% of Vdd Minimum or No Connection to Enable Output, 30% of Vdd Maximum to Disable Output (Disabled Output High Impedance)
Standby Current	Pad 1=Ground 50µA Maximum (Disabled Output: Logic Low)
Disable Current	Pad 1=Ground 20mA Maximum (Disabled Output: High Impedance)
Spread Spectrum Input Voltage (Vih and Vil)	70% of Vdd Minimum or No Connection to Enable Spread Spectrum-On Output, 30% of Vdd Maximum to Disable Spread Spectrum-On Output (Spread Spectrum On Output Disabled)
Spread Spectrum	±0.25% Center Spread (Not available with Output Control Function of Spread Disable) ±0.50% Center Spread (Not available with Output Control Function of Spread Disable) ±1.00% Center Spread (Not available with Output Control Function of Spread Disable) -0.50% Down Spread -1.00% Down Spread -2.00% Down Spread
Modulation Frequency	30kHz Minimum, 32kHz Typical, 35kHz Maximum
Period Jitter	Cycle to Cycle; Spread Spectrum-On; Fo=133.333M, Vdd=2.5Vdc 40pSec Maximum
Start Up Time	10mSec Maximum

Storage Temperature Range	-55°C to +125°C

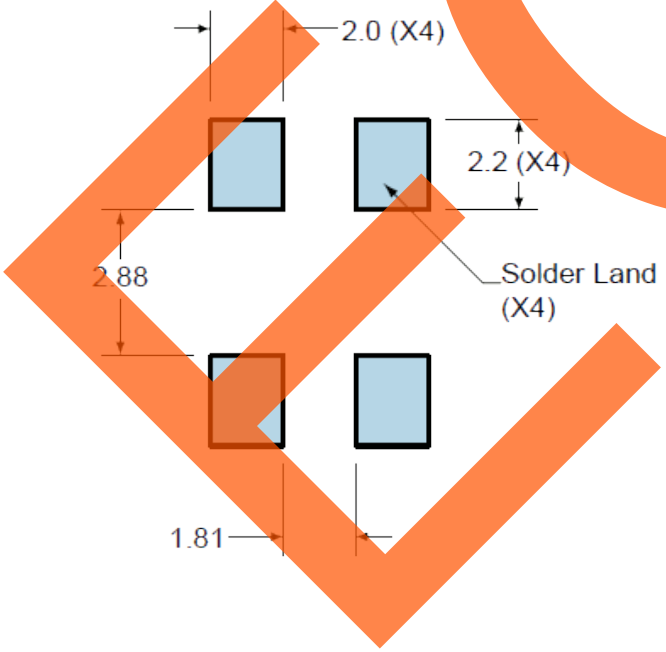
PART NUMBERING GUIDE



MECHANICAL DIMENSIONS



SUGGESTED SOLDER PAD LAYOUT

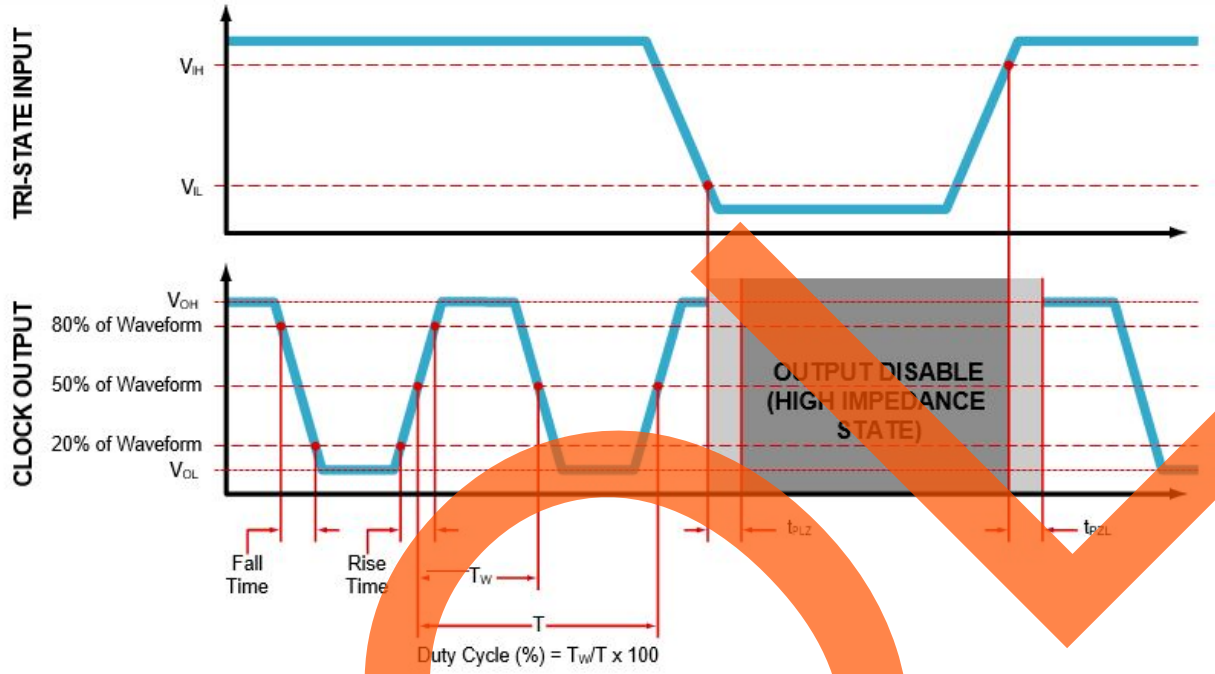


PIN	CONNECTION
1	Power Down Or Spread Disable Or Tri-State
2	Ground
3	Output
4	Supply Voltage

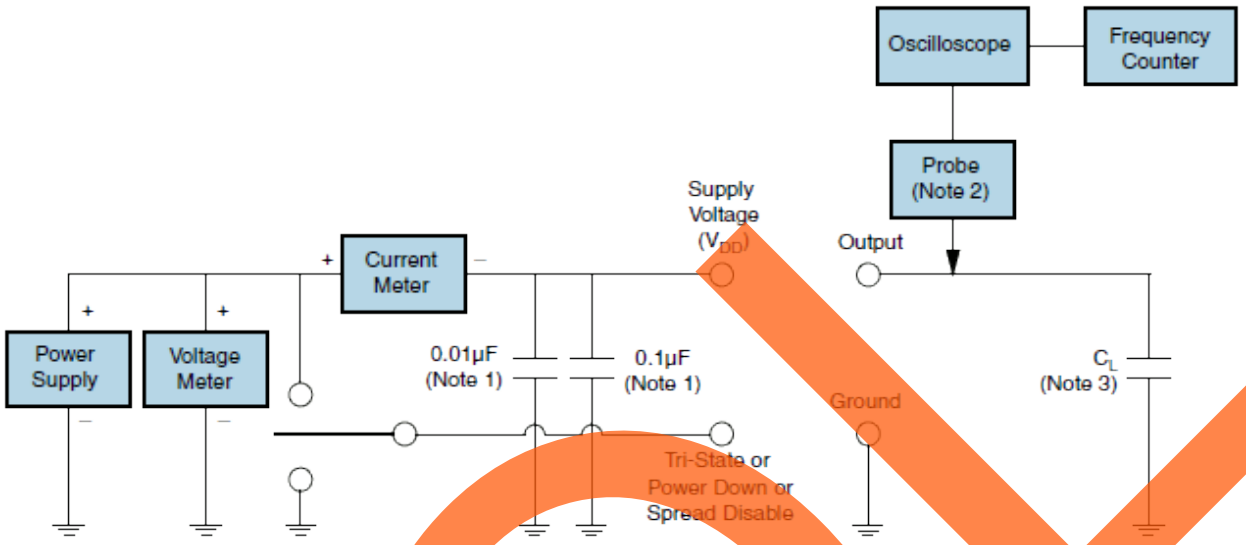
All Tolerances are ±0.1

All Dimensions in Millimeters

OUTPUT WAVEFORM & TIMING DIAGRAM



TEST CIRCUIT FOR CMOS OUTPUT



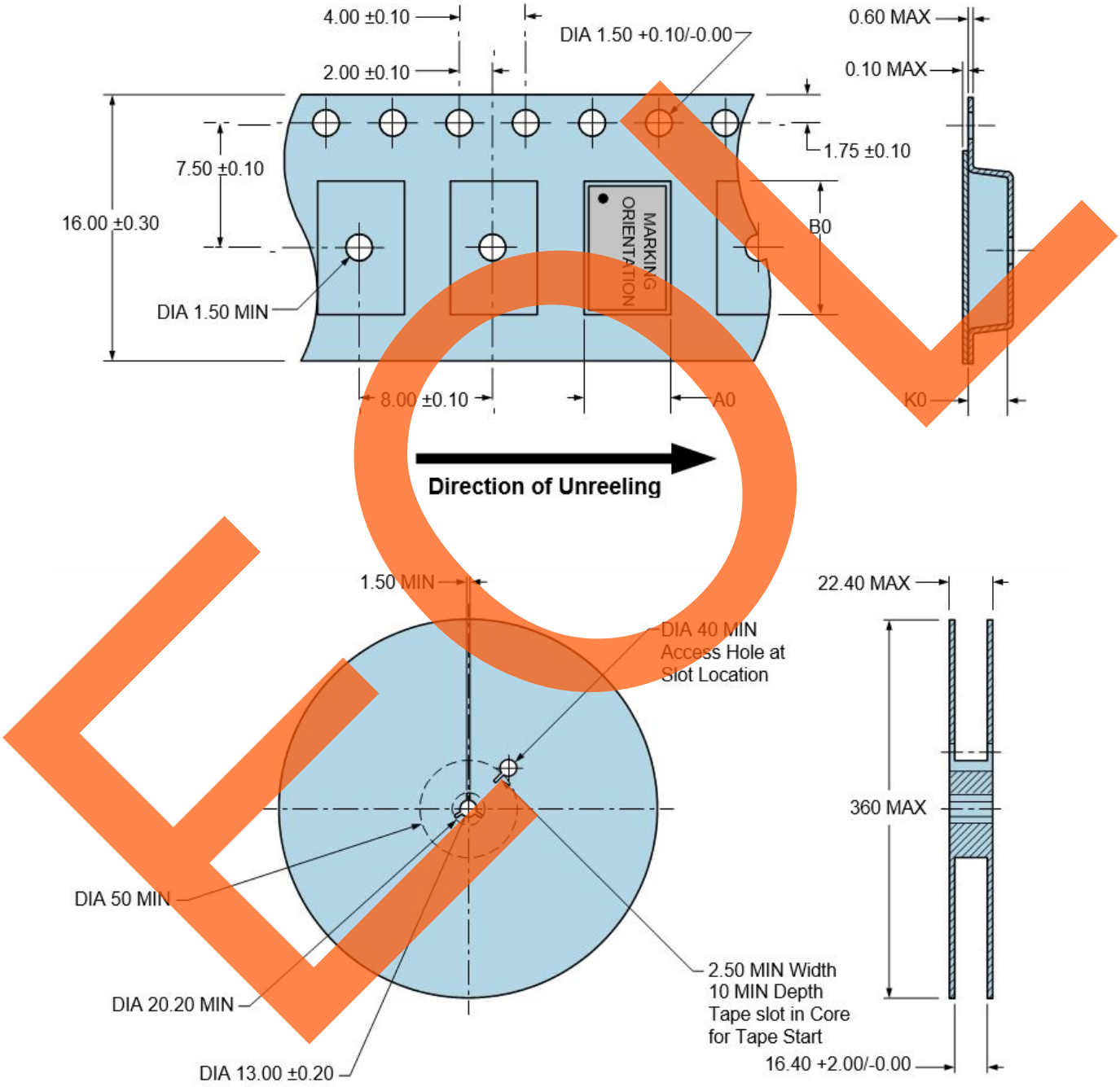
Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less Than 2mm) to the package ground and supply voltage pin is required.
Note 2: A low capacitance (<12pF), 10X Attentuation Factor, High Impedance (>10Mohms), and High bandwidth (>300MHz) Passive probe is recommended.
Note 3: Capacitance value (C_L) includes sum of all probe and fixture capacitance.

TAPE & REEL DIMENSIONS

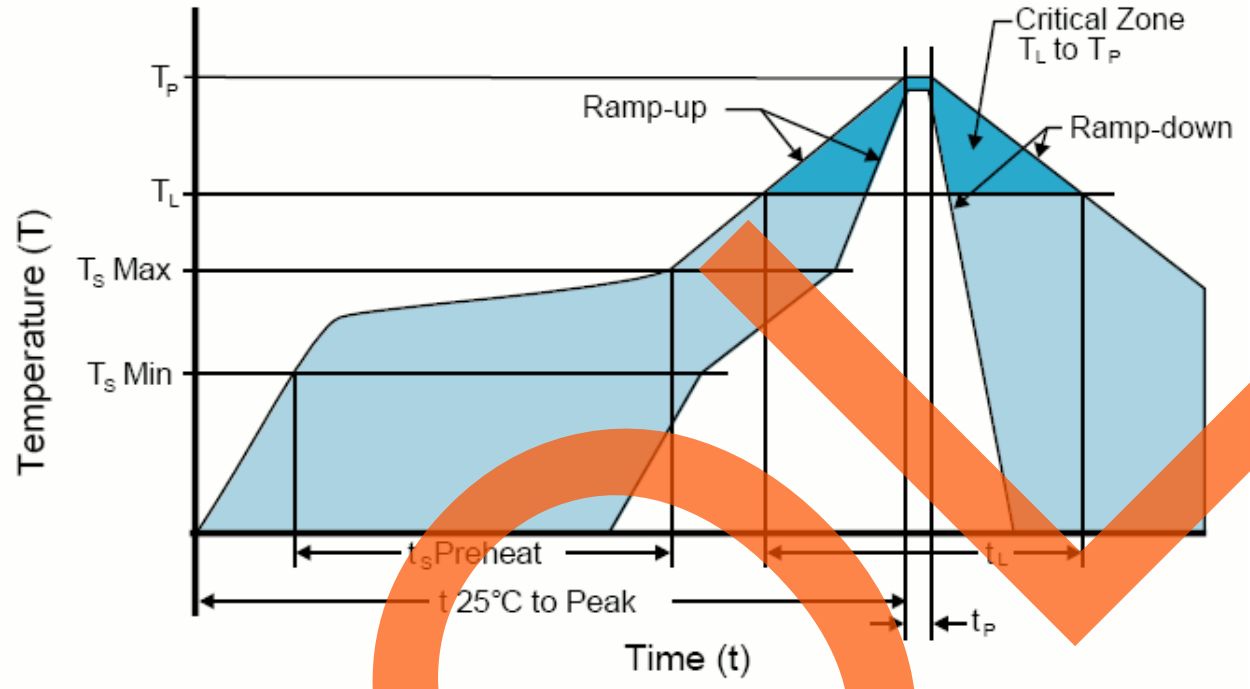
Quantity per Reel: 1000 Units

All Dimensions in Millimeters

Compliant to EIA-481



RECOMMENDED SOLDER REFLOW METHOD

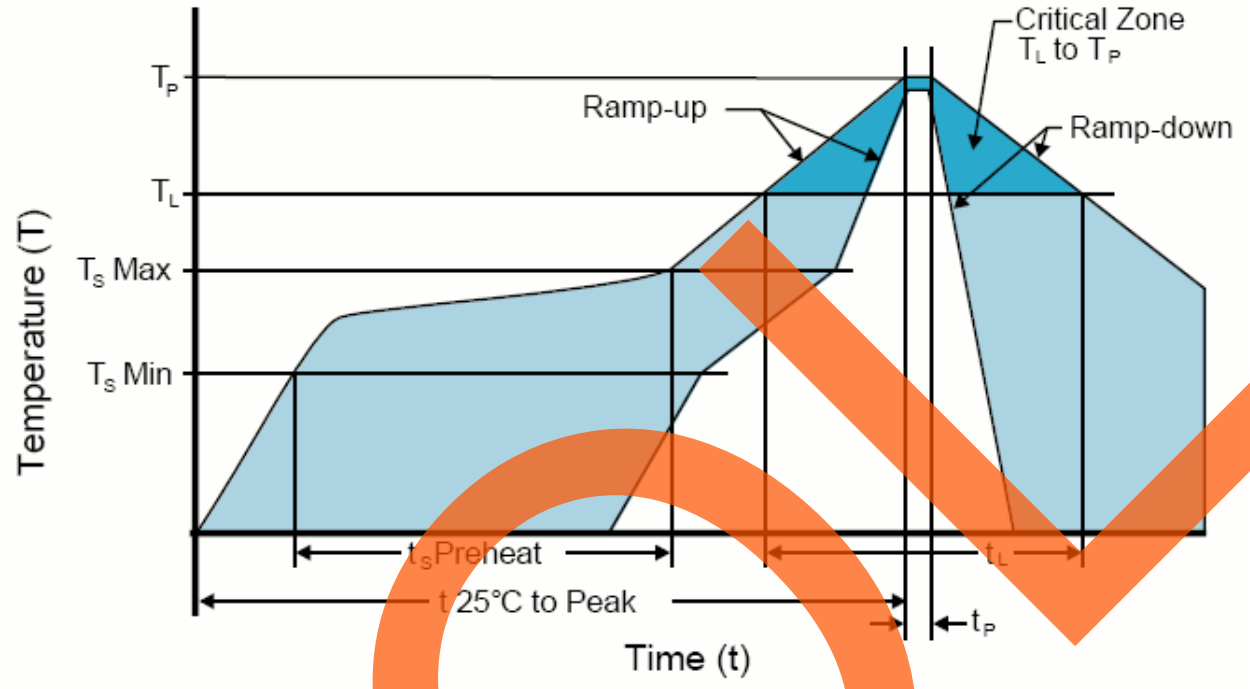


HIGH TEMPERATURE INFRARED/CONVECTION	
T_S MAX to T_L (Ramp-up Rate)	3°C/Second Maximum
Preheat - Temperature Minimum (T_S MIN) - Temperature Typical (T_S TYP) - Temperature Maximum(T_S MAX) - Time (t_S)	 150°C 175°C 200°C 60 - 180 Seconds
Ramp-up Rate (T_L to T_P)	3°C/Second Maximum
Time Maintained Above: - Temperature (T_L) - Time (t_L)	 217°C 60 - 150 Seconds
Peak Temperature (T_P)	260°C Maximum for 10 Seconds Maximum
Target Peak Temperature(T_P Target)	250°C +0/-5°C
Time within 5°C of actual peak (t_p)	20 - 40 Seconds
Ramp-down Rate	6°C/Second Maximum
Time 25°C to Peak Temperature (t)	8 Minutes Maximum
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures shown are applied to body of device.

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

RECOMMENDED SOLDER REFLOW METHOD



LOW TEMPERATURE INFRARED/CONVECTION	
T_S MAX to T_L (Ramp-up Rate)	5°C/Second Maximum
Preheat **- Temperature Minimum (T_s MIN)** **- Temperature Typical (T_s TYP)** **- Temperature Maximum(T_s MAX)** **- Time (t_s)**	 N/A 150°C N/A 60 - 120 Seconds
Ramp-up Rate (T_L to T_P)	5°C/Second Maximum
Time Maintained Above: **- Temperature (T_L)** **- Time (t_L)**	 150°C 200 Seconds Maximum
Peak Temperature (T_P)	240°C Maximum
Target Peak Temperature (T_P Target)	240°C Maximum 2 Times / 230˚C Maximum 1 Time
Time within 5°C of actual peak (t_p)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures shown are applied to body of device.

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)